



MD[®] 1405-M-UR-SC

LED-Optimized Adhesive with Encompass[®] Technology for Plastics and Metals

APPLICATIONS	FEATURES	RECOMMENDED SUBSTRATES	BIOCOMPATIBILITY
<ul style="list-style-type: none"> Syringes Blood Transfer Devices Winged Infusion Sets Collection Sets Dialyzers Combination Devices 	<ul style="list-style-type: none"> LED Optimized 385/405 nm Blue-to-Colorless Upon Cure Ultra-Red[®] Fluorescing Deeper Section Cure 	<ul style="list-style-type: none"> ABS PC PCTG PETG PMMA SAN 	<ul style="list-style-type: none"> ISO 10993-5 Cytotoxicity ISO 10993-6 Implantation ISO 10993-11 Systemic Toxicology ISO 10993-23 Intracutaneous Irritation

Dymax MD[®] 1405-M-UR-SC with Encompass[®] technology is designed to be cured with either 385 nm or 405 nm UV wavelength light sources for rapid bonding of multiple substrates typically used in the manufacture of medical device assemblies. Encompass technology combines patented See-Cure and Ultra-Red[®] technologies. Products with Dymax See-Cure technology dispense blue and transition to colorless upon full cure. This aids in verification of adhesive placement and facilitates in the validation of manufacturing processes. Ultra-Red fluorescing technology contrasts extremely well on plastics which normally fluoresce blue under low-intensity black light (365 nm). This allows for easy inspection of post-cure bond lines. Dymax MD Medical Device Adhesives contain no nonreactive solvents and cure upon exposure to light. Their ability to cure in seconds enables faster processing, greater output, and lower processing costs. When cured with Dymax light-curing spot lamps, focused-beam lamps, or flood lamps, they deliver optimum speed and performance for medical device assembly. Dymax lamps offer the ideal balance of UV and visible light for the fastest, deepest cures. This product is in full compliance with RoHS directives 2015/863/EU.

UNCURED PROPERTIES *		
Property	Value	Test Method
Solvent Content	No Nonreactive Solvents	N/A
Chemical Class	Acrylated Urethane	N/A
Appearance	Blue Transparent Liquid	N/A
Soluble in	Organic Solvents	N/A
Density, g/ml	1.05	ASTM D1875
Viscosity, cP	150 (nominal)	DSTM 502‡
Shelf Life at Recommended Conditions from Date of Manufacture	8 months	N/A

CURED MECHANICAL PROPERTIES *		
Property	Value	Test Method
Durometer Hardness	D70	ASTM D2240
Tensile at Break, MPa [psi]	18.6 [2,700]	ASTM D638
Elongation at Break, %	150	ASTM D638
Modulus of Elasticity, MPa [psi]	397 [57,600]	ASTM D638

OTHER CURED PROPERTIES *		
Property	Value	Test Method
Appearance	Colorless	N/A
Refractive Index (20°C)	1.51	ASTM D542
Boiling Water Absorption, % (2 h)	4.4	ASTM D570
Water Absorption, % (25°C, 24 h)	3.2	ASTM D570
Linear Shrinkage, %	0.4	ASTM D2566
Glass Transition Tg, °C	99	ASTM D5418
CTE _{α1} , μm/m/°C	72	ASTM E831
CTE _{α2} , μm/m/°C	280	ASTM E831

* Not Specifications

N/A Not Applicable

‡ DSTM Refers to Dymax Standard Test Method

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Technical Data Collected Prior to 2017 Rev.06/06/2024





MD® MEDICAL DEVICE ADHESIVES
1405-M-UR-SC Product Data Sheet

ADHESION	
Substrate	Recommendation
ABS acrylonitrile-butadiene-styrene	✓
PA polyamide	o
PC polycarbonate	✓
PCTG poly(cyclohexylene dimethylene terephthalate)glycol	✓
PEI polyetherimide	✓
PET poly(ethylene terephthalate)	✓
PETG poly(ethylene terephthalate)glycol	✓
PI polyimide	o
PMMA poly(methyl methacrylate)	✓
PPO poly(phenylene oxide)	✓
PS polystyrene	✓
PU polyurethane	✓
PVC poly(vinyl chloride)	o
SAN styrene-acrylonitrile	✓
TPU thermoplastic polyurethane	o
AL aluminum	o
SS stainless steel	✓
PCB printed circuit board	✓

✓ Recommended o Limited Applications
 st Requires Surface Treatment (e.g. plasma, corona treatment, etc.)



CURING GUIDELINES

The vivid blue color of this adhesive transitions to colorless when fully cured. The charts below provide information on cure time required to transition from blue to colorless using different light sources and adhesive thicknesses. Cure rate is dependent upon many variables including lamp intensity, distance from the light source, and required depth of cure. The times and belt speed for the transition listed below are based on lab results and are intended for reference only.

Dymax Curing System (Intensity)	5000-EC (200 mW/cm ²) ^B
Adhesive Thickness, mm [mil]	Time to complete transition, s ^A
0.10 [4.0]	2
0.20 [8.0]	3
0.41 [16]	5
0.81 [32]	9

Dymax Curing System (Intensity)	BlueWave® 200 (10 W/cm ²) ^{B E}
Adhesive Thickness, mm [mil]	Time to complete transition, s ^A
0.10 [4.0]	0.6
0.20 [8.0]	0.8
0.41 [16]	2
0.81 [32]	3

Dymax Curing System (Intensity)	BlueWave® MX-150 PrimeCure® 385 nm (15 W/cm ²) ^{C E}
Adhesive Thickness, mm [mil]	Time to complete transition, s ^A
0.10 [4.0]	1
0.20 [8.0]	2
0.41 [16]	2
0.81 [32]	3

Dymax Curing System (Intensity)	BlueWave® MX-150 VisiCure® 405 nm (15 W/cm ²) ^{C E}
Adhesive Thickness, mm [mil]	Time to complete transition, s ^A
0.10 [4.0]	4
0.20 [8.0]	5
0.41 [16]	5
0.81 [32]	10

^A Curing through light-blocking substrates may limit the ability of See-Cure adhesives to transition from blue to clear and may require longer light exposure at critical wavelengths (320-400 nm for UV light curing; 20-450 nm for UV/Visible light curing). These time s/speeds are typical for curing through 100% light-transmitting substrates.

^B Intensity was measured over the UVA range (320-395 nm) using a Dymax ACCU-CAL™ 50 Radiometer.

^C Intensity was measured over the UVA/Visible range (250-450 nm) using a Dymax ACCU-CAL™ 50-LED Radiometer.

^D At 53 mm [2.1 in] focal distance. Maximum speed of conveyor is 8.2 m/min [27 ft/min]. Intensity was measured over the UVA range (320-395 nm) using the Dymax ACCU-CAL™ 160 Radiometer.

^E Due to the distance between the end of the lightguide and adhesive, intensity at the curing area was measured as 4.0W/cm².

Full cure is best determined empirically by curing at different times and intensities, and measuring the corresponding change in cured properties such as tackiness, adhesion, hardness, etc. Full cure is defined as the point at which more light exposure no longer improves cured properties. Higher intensities or longer cures (up to 5x) generally will not degrade Dymax light-curable adhesives.

Dymax recommends that customers employ a safety factor by curing longer and/or at higher intensities than required for full cure. Although Dymax Application Engineering can provide technical support and assist with process development, each customer ultimately must determine and qualify the appropriate curing parameters required for their unique application.



OPTIMIZING PERFORMANCE AND HANDLING

1. This product cures with exposure to UV and visible light. Exposure to ambient and artificial light should be kept to a minimum before curing. Dispensing components including needles and fluid lines should be 100% light blocking, not just UV blocking.
2. All bond surfaces should be clean and free from grease, mold release, and other contaminants prior to dispensing the adhesive.
3. Cure and color transition speed are dependent upon many variables, including lamp intensity, distance from the light source, required depth of cure, bond gap, and percent light transmission of the substrate.
4. Oxygen in the atmosphere may inhibit surface cure. Surfaces exposed to air may require high-intensity (>150 mW/cm²) UV light to produce a dry surface cure. Flooding the bond area with an inert gas, such as nitrogen, can also reduce the effects of oxygen inhibition.
5. Parts should be allowed to cool after cure before testing and subjecting to any loads.
6. In rare cases, stress cracking may occur in assembled parts. Three options may be explored to eliminate this problem. One option is to heat anneal the parts to remove molded-in stresses. A second option is to open the gap between mating parts to reduce stress caused by an interference fit. The third option is to minimize the amount of time the liquid adhesive remains in contact with the substrate(s) prior to curing.
7. Light curing generally produces some heat. If necessary, cooling fans can be placed in the curing area to reduce the heating effect on components.
8. At the point of curing, an air exhaust system is recommended to dissipate any heat and vapors formed during the curing process.

DISPENSING SUPPORT

The Dymax Application Engineering team is ready to discuss your application requirements to provide the most appropriate dispensing and/or spraying solution. Visit our current dispensing equipment portfolio [here](#) or consult our [global contact](#) phone numbers and online chat feature (available in North America only) during normal business hours for instant support.

STORAGE AND SHELF LIFE

Store the material in a cool, dark place when not in use. Do not expose to light. This product may polymerize upon prolonged exposure to ambient and artificial light. Keep covered when not in use. This material shelf life noted on page 1 of this document, when stored between 10°C (50°F) and 32°C (90°F) in the original, unopened container.

STERILIZATION

Compatible sterilization methods include gamma irradiation and ethylene oxide. Sterilization by autoclaving may be limited to certain applications. It remains the user's obligation to ascertain the effect of sterilization on the cured adhesive.

CLEAN UP

Uncured material may be removed from dispensing components and parts with organic solvents. Cured material will be impervious to many solvents and difficult to remove. Cleanup of cured material may require mechanical methods of removal.

BIOCOMPATIBILITY

Polymerized Dymax MD® Medical Device Adhesives are biocompatibility tested in accordance with ISO 10993 and/or USP Class VI. The completed tests are listed on each product data sheet. Copies of the test reports are available upon request. In all cases, it is the user's responsibility to determine and validate the suitability of these adhesives in the intended medical device. These adhesives have not been tested for prolonged or permanent implantation, and are only intended for use in short-term (<29 days) or single-use disposable-device applications. Dymax does not authorize their use in long-term implant applications. Customers using these materials for such applications do so at their own risk and take full responsibility for ensuring product safety and biocompatibility.



GENERAL INFORMATION

This product is intended for industrial use only. Keep out of the reach of children. Avoid breathing vapors. Avoid contact with skin, eyes, and clothing. Wear impervious gloves. Repeated or continuous skin contact with uncured material may cause irritation. Remove material from skin with soap and water. Never use organic solvents to remove material from skin and eyes. For more information on the safe handling of this material, please refer to the Safety Data Sheet before use.

The data provided in this document are based on historical testing that Dymax performed under laboratory conditions as they existed at that time and are for informational purposes only. The data are neither specifications nor guarantees of future performance in a particular application. Dymax does not guarantee that this product's properties are suitable for the user's intended purpose.

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